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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







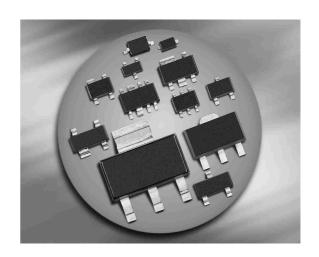


NPN Silicon Digital Transistor

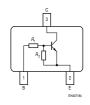
- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor (R_1 =47k Ω , R_2 =22k Ω)
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101







BCR146



Туре	Marking	Pin Configuration			Package			
BCR146	WLs	1=B	2=E	3=C	-	-	-	SOT23

Maximum Ratings

Parameter	Symbol	Value	Unit	
Collector-emitter voltage	$V_{\sf CEO}$	50	V	
Collector-base voltage	V_{CBO}	50		
Input forward voltage	V _{i(fwd)}	80		
Input reverse voltage	V _{i(rev)}	10		
Collector current	I _C	70	mA	
Total power dissipation-	P _{tot}	200	mW	
<i>T</i> _S ≤ 102°C				
Junction temperature	$T_{\rm j}$	150	°C	
Storage temperature	T _{stq}	-65 150		

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	≤ 240	K/W

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2011-08-29



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

/(BR)CEO /(BR)CBO	min. 50	typ.	max.	V
, ,		-	-	V
, ,		-	-	V
(BR)CBO	50			
(BR)CBO	EΟ			
	50	-	-	
СВО	-	-	100	nA
EBO	-	-	220	μA
) _{FE}	50	-	-	-
CEsat	1	-	0.3	V
/i(off)	1.2	-	2.6	
/ _{i(on)}	1.5	-	4	
, ,				
₹1	32	47	62	kΩ
R_1/R_2	1.92	2.14	2.36	-
·	<u> </u>		·	•
Г	-	150	-	MHz
Ccb	-	3	-	pF
	EBO FE CEsat (i(off) (i(on)	FE 50 CEsat - (i(off) 1.2 Calculate 32 C	EBO	FE 50 220 (CEsat 0.3 (i(off) 1.2 - 2.6 (i(on) 1.5 - 4 (2.1 32 47 62 (2.1/R ₂ 1.92 2.14 2.36

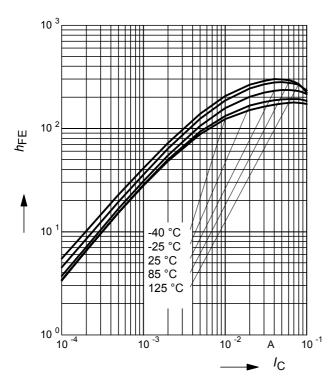
 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

 $^{^{2}}$ Pulse test: t < 300 μ s; D < 2%



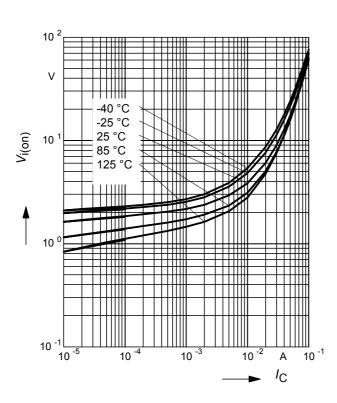
DC current gain $h_{FE} = f(I_C)$

 V_{CE} = 5V (common emitter configuration)



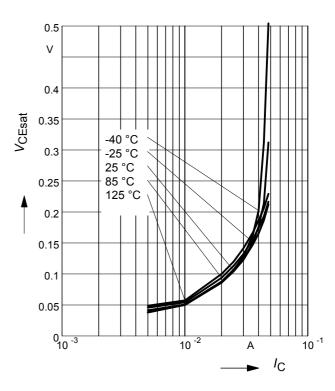
Input on Voltage $Vi_{(On)} = f(I_C)$

 V_{CE} = 0.3V (common emitter configuration)



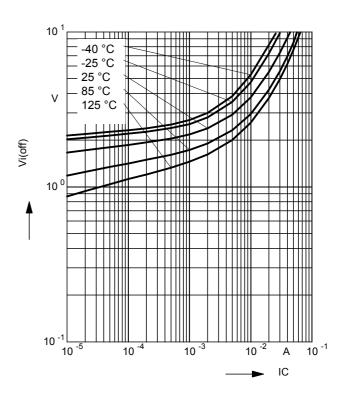
Collector-emitter saturation voltage

 $V_{CEsat} = f(I_{C}), I_{C}/I_{B} = 20$



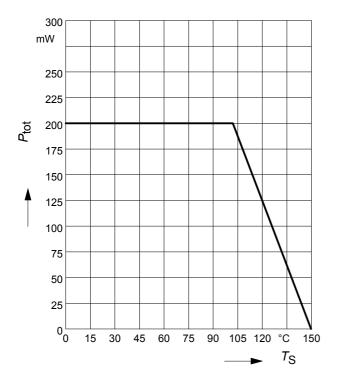
Input off voltage $V_{i(Off)} = f(I_C)$

 V_{CE} = 5V (common emitter configuration)

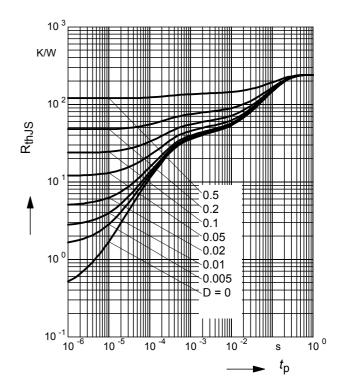




Total power dissipation $P_{tot} = f(T_S)$ BCR146



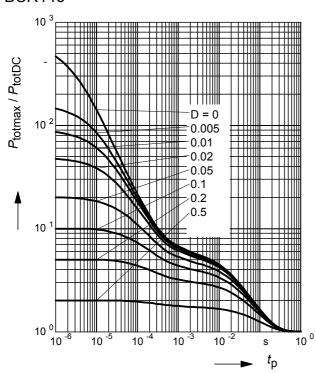
Permissible Pulse Load $R_{thJS} = f(t_p)$ BCR146



Permissible Pulse Load

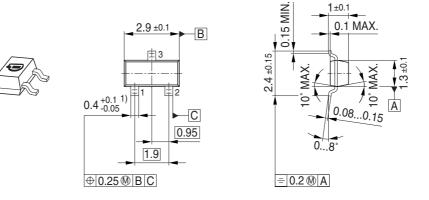
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$$

BCR146

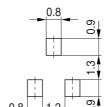




Package Outline

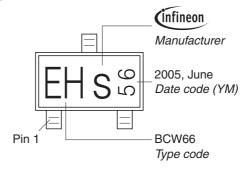


Foot Print



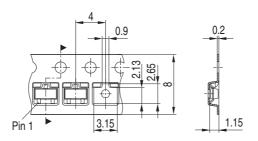
1) Lead width can be 0.6 max. in dambar area

Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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